

Title (en)
NONSTICK MATERIAL, METHOD FOR REMOVING A PART OF A PLANAR MATERIAL LAYER AND MULTILAYER STRUCTURE AND USE THEREFOR

Title (de)
HAFTVERHINDERUNGSMATERIAL, VERFAHREN ZUM ENTFERNEN EINES TEILBEREICHES EINER FLÄCHIGEN MATERIALSCHICHT SOWIE MEHRLAGIGE STRUKTUR UND VERWENDUNG HIERFÜR

Title (fr)
MATIERE INHIBITRICE D'ADHERENCE, PROCEDE POUR ENLEVER UNE PORTION D'UNE COUCHE DE MATIERE PLANE, STRUCTURE MULTICOUCHE ET LEUR UTILISATION.

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Application
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Abstract (en)
[origin: WO2008098271A1] The invention relates to a nonstick material for use during removal of a part (11) of a substantially planar material layer (2) which is connected in a connecting step to at least one further, substantially planar material layer (9). According to the invention, the nonstick material (8) has a different polarity than the adjoining, substantially planar material layers (2, 9). The invention also relates to a method for removing a part (11) of a substantially planar material layer (2) which is connected in a connecting step to at least one further, substantially planar material layer (9), to a multilayer structure which consists of at least two substantially planar material layers (2, 9) to be interconnected, and to a use of the same, especially in a multilayer printed circuit board.

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Citation (search report)
See references of WO 2008098271A1

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JP H1022645 A 19980123 - NIPPON AVIONICS CO LTD

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